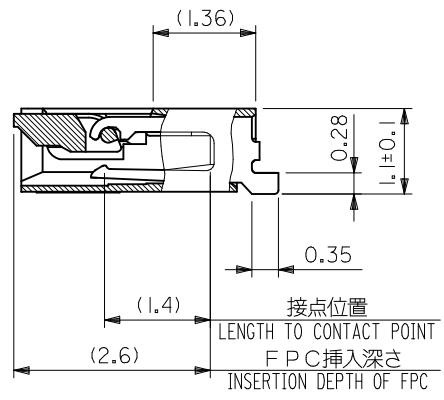
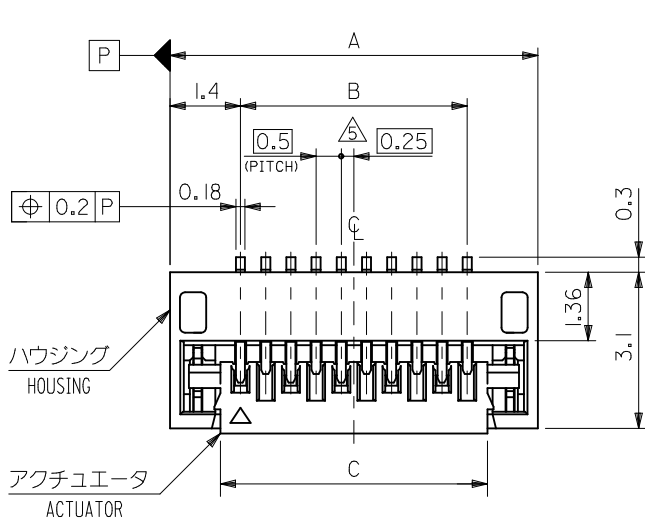
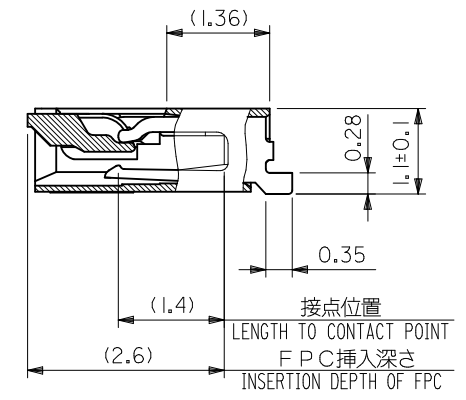


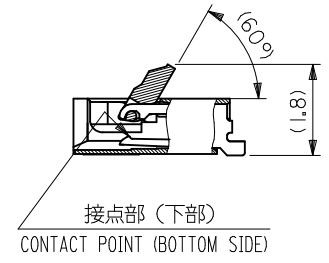
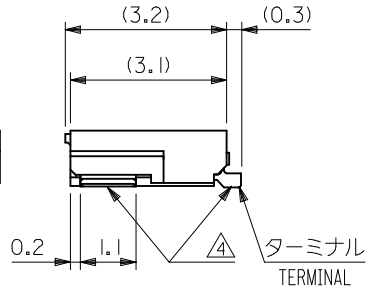
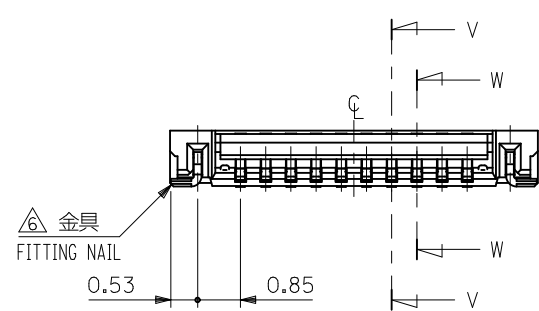
10 9 8 7 6 5 4 3 2 1



断面 V-V 奇数極  
SECT. V-V (ODD CKT)



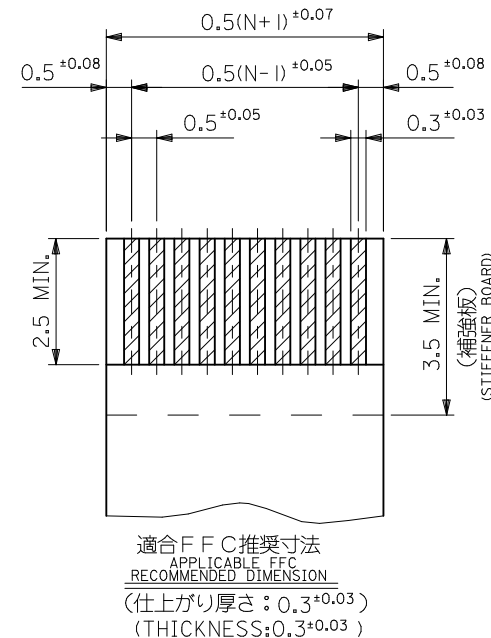
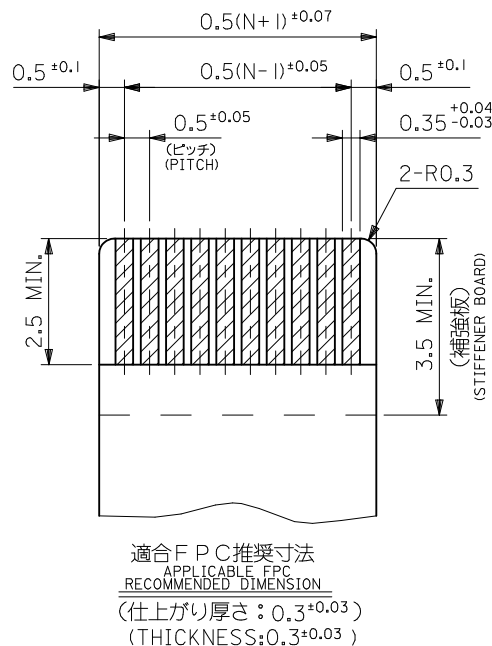
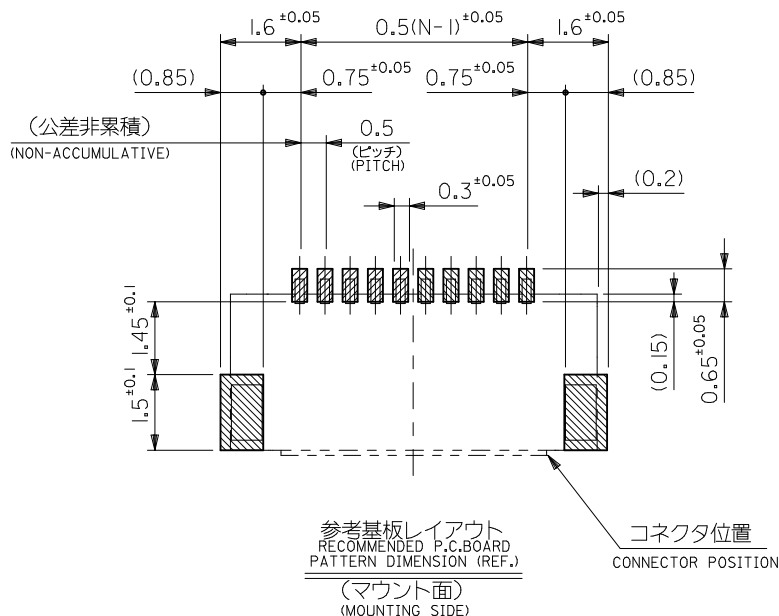
断面 W-W 偶数極  
SECT. W-W (EVEN CKT)



(アクチュエータが開いた状態)  
(WHEN ACTUATOR IS OPENED)

12.3	11.5	14.3	51441-2472	24
11.3	10.5	13.3	51441-2272	22
10.3	9.5	12.3	51441-2072	20
6.3	5.5	8.3	51441-1272	12
5.8	5.0	7.8	51441-1172	11
5.3	4.5	7.3	51441-1072	10
4.3	3.5	6.3	51441-0872	8
C	B	A	EMBOSSED TAPE	極数
			ORDER No. オーダー番号	CIRCUIT
CONNECTOR SERIES NO. 51441-**28				

REVISED EC NO: J2010-1656 DRWN: TONO 2010/02/15 CHKD: SHIMOMIYAMA 2010/02/15 APPR: KMORIKAWA 2010/02/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '05/06/29	TITLE 0.5 FPC CONN. (E/O) HSG ASSY BTM CONT(H=1.1)			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE '05/06/29	MOLEX INCORPORATED DOCUMENT NO. SD-51441-012 SHEET NO. 1 OF 2			
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE '05/06/29				
		ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー ガラス充填, UL94V-0 (ベージュ)  
HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)  
アクチュエータ: ポリフェニレンサルファイド ガラス充填, UL94V-0 (黒)  
ACTUATOR POLYPHENYLENE SULFIDE GLASS FILLED, UL94V-0(BLACK)  
ターミナル : リン青銅 (t=0.18)  
TERMINAL PHOSPOR BRONZE  
金具 : リン青銅 (t=0.15)  
FITTING NAIL PHOSPOR BRONZE

3. エンボステープ梱包時は、アクチュエータが閉じた状態とする。  
IN THE PACKAGE, ACTUATOR OF PART NO.51441-\*\*-II SHOULD BE CLOSED.
- △ソルダータール及び金具の平坦度は、0.1以下。  
SOLDER TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.
- △偶数極に適用。  
APPLY FOR EVEN CIRCUIT.
- △パターンはくり止め用金具  
FITTING NAIL FOR PREVENTION OF PEELING OF PCB PATTERN.
7. 本製品は 51441-\*\*-29 の部分金メッキ品である。  
THIS PRODUCT IS SELECTIVE GOLD OF 51441-\*\*-29.
8. ELV AND RoHS COMPLIANT.

2. メッキ仕様 PLATING

ターミナル TERMINAL  
ニッケル下地金メッキ  
GOLD OVER NICKEL PLATING

金具 FITTING NAIL  
ニッケル下地金メッキ  
TIN OVER NICKEL PLATING

FPC/FFCについて:

打抜き方向は導体側から補強板側を推奨いたします。  
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨いたします。  
ABOUT FPC/FFC  
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPEC :  
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER

FPCについて:

補強フィルム材質はポリイミドを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
ABOUT FPC  
RECOMMENDED MATERIAL :  
STIFFENER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2010-1656 DRWN: TONO 2010/02/15 CHKD: HSHIMOIYAMA 2010/02/15 APPR: KMORIKAWA 2010/02/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER	±0.2	DRAWN BY M. NABEI	DATE '05/06/29	TITLE 0.5 FPC CONN. (E/O) HSG ASSY BTM CONT(H=1.1)		
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOYODA	DATE '05/06/29	MOLEX INCORPORATED		
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE '05/06/29	DOCUMENT NO. SD-51441-012		
		ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			SHEET NO. 2 OF 2